

DEVICE CHARACTERIZATION AND MODELING

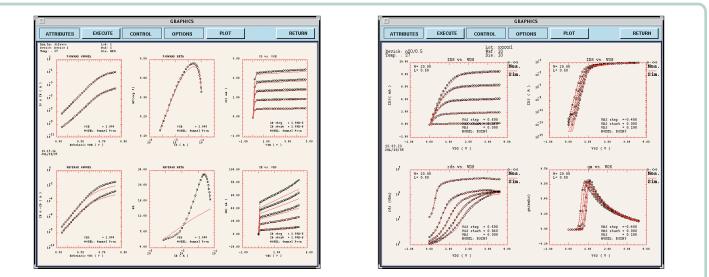


UTMOST III generates accurate, high quality SPICE models for analog, mixed-signal and RF applications. UTMOST III is in use worldwide by leading IDMs, foundries and fabless companies to perform data acquisition, device characterization, model parameter extraction and model verification.

- UTMOST III supports the characterization and model extraction for MOS, BJT, Diode, JFET, GaAs, SOI and TFT devices
- UTMOST III provides the widest selection of measurement equipment from a variety of vendors
- Fully interactive, semi-automated or batch-mode operation is supported
- Real-time model tuning using the rubberband feature
- Integrated with Silvaco TCAD Software and SPAYN statistics program for smooth development of pre-silicon models
- Supports all leading SPICE simulators
- Silvaco's strong encryption is available to protect valuable customer and third party intellectual property

Test and Analysis Environment

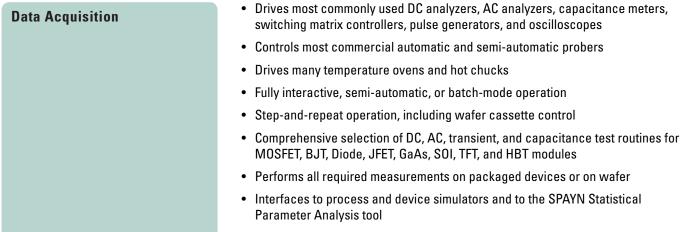
- Flexible measurement and analysis environment for device characterization and model generation
- Supports widest selection of instrument drivers, prober drivers, device models, operating platforms, and commercial circuit simulators
- Splits device characterization and/or modeling problems into separate measurement and analysis tasks
- Stores measured results in measurement log files for future analysis (search, averaging) so that valuable probe time is minimized
- · Common data sets can be used to extract more than one model type
- · Supports single test or step-and-repeat operation
- Extracts parameters by using comprehensive library of built-in extraction algorithms, flexible user-defined local optimization strategies, more interactive global optimization procedures, or a combination of all three
- Stores extracted parameters in multiple formats, including SPICE library formats that can be read back into UTMOST III as an initial estimate during future model extractions



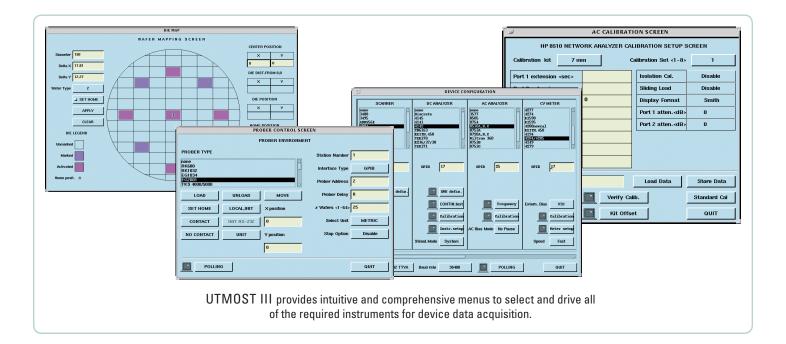
UTMOST III acquires measured or TCAD simulated data, extracts parameters, and delivers accurate, high quality SPICE models.

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UTMOST III addresses the practical needs of device characterization and modeling engineers with a flexible, productive workflow

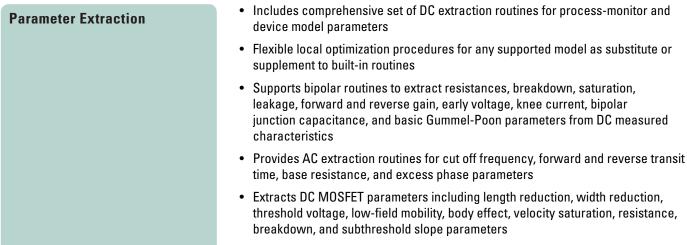


· Supports the widest variety of models and circuit simulators

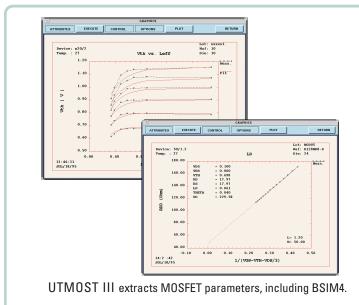


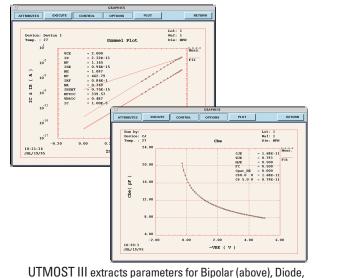
UTMOST III supports the widest selection of instruments

DC Analyzers	AC Analyzers	Scanners	Capacitance Meters	Probers
B1500A	HP3577	B2200/B2201	B1500A-B1520A	Alessi 4500
HP4141	HP8505	HP3488	HP4262	Alessi 5500
HP4142	HP8510A,B,C	HP3495	HP4271	Cascade Summit
HP4145	HP8720A,B,C,D,E	HP3852A	HP4284	Electroglas 1034
HP4155/56	HP8722D	HP4084	HP4285	Electroglas 2001
	HP8751	HP4085	HP4192	Electron
Keithley 236	HP8753A,B,C,D,E	HP4086	HP4194	Karl Suss (PE100/PA200 II)
Keithley 237	HP8754	Keithley 705	HP4274	RK 680
Keithley 238	Wiltron 360	Keithley 706	HP4275, HP4276, HP4277	RK 681
Keithley 4200		Keithley 707	HP4279	RK 1032
Keithley S450		Keithley 7002	HP4280	TKS 3000
Tektronics 370/370A		RACAL 1251	HP4294A	TKS 4000
Tektronics 371/371A			E4980A	TKS 5000
			Keithley 590	TKS 6000
			Keithley 595	Tokyo
				Wentworth MP-1100



· Supports the extraction of overlap and junction capacitance parameters





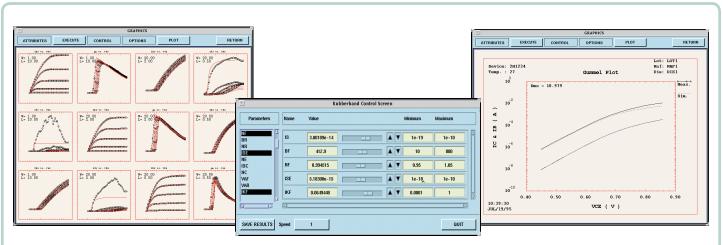
JFET, GaAs, SOI, TFT, HBT, and passive devices for RF.

Advanced Parameter Extraction

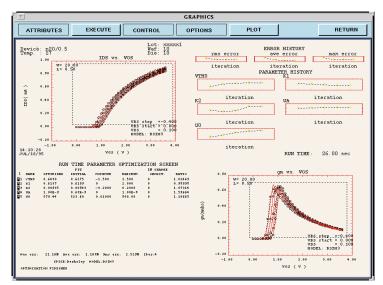
- SOI module permits characterization of all transistor properties, including 4/5 terminals device, bipolar parasitic effects, and Body or BackGate currents
- · Measured s-parameters can be converted to h, z, and y-parameters
- Supports standard, calibration and two step de-embedding procedures for correct measurement of s-parameters
- Includes special extraction algorithms for the extraction of BSIM1, BSIM2, BSIM3, BSIM4, MOS9 and MOS11 parameters, for single or multiple geometries
- Universal multi-target / multi-geometry measurement routine for SOI and MOS technology
- · Gate current measurement and parameter extraction routine for BSIM4, MOS11

Parameter Optimization

- Offers flexible local optimization facility and global parameter optimization boundary boxes
- Optimize multiple device geometries simultaneously (up to 36 devices) and mix device currents and conductances as optimization targets
- Rubberband interactive parameter extraction enables modeling engineers to observe the effects of parameter variations on device characteristics
- Supports single or multi-geometry optimization with graphical updating of simulated characteristics
- · Supports multi-step optimization all in real-time
- Supports graphical parameter sensitivity and quality-of-fit information



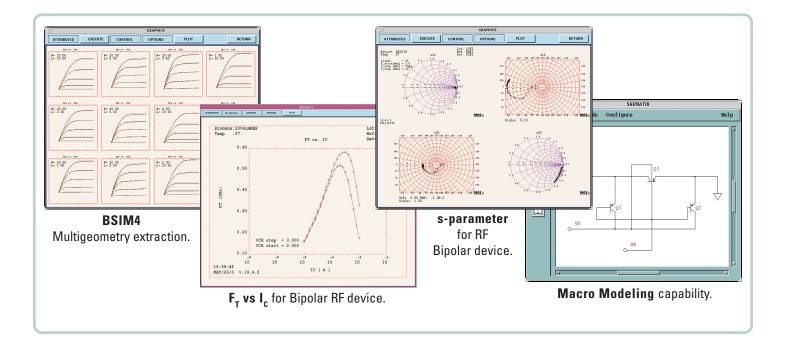
Optimized MOS model (left), Rubberband user interface (middle), and Optimal Bipolar model results (right).



UTMOST III supports Levenberg-Marquadt and Downhill Simplex optimization methods.

Model Generation

- · Supports widest selection of commercially available device models
- Generates models for SmartSpice, HSPICE, Spectre and ELDO
- Offers fast built-in SPICE simulation library (ModelLib statically linked: cannot benefit from flexibility as UTMOST IV)
- · External SPICE mode allows you to connect to any SPICE simulator
- Supports the conversion of model parameter sets from one model to another
- Macro modeling and parameter extraction is available for devices which cannot be adequately modeled by any existing device models
- · User-defined models linked dynamically
- Support for SmartSpice interpreter models
- · Fast simulation using ModelLib Model and Fast internal solver



Supported SPICE Models

MOSFET models

Berkeley Level 1 Berkeley Level 2 Berkeley Level 3 BSIM1 BSIM2 BSIM3 BSIM4 BSIMMG BSIM5 PSP Level 1000 Philips Level 9 EKV LDMOS Level 20 Philips Level 11 User models HV MOS Level 88 HiSIM Philips 30 Philips 31

Bipolar models Gummel-Poon Quasi BC

Quasi RC IGBT QBBJT MEXTRAM HBT HICUM MEXTRAM504 User models Mextram 503 VBIC95 Philips Modella

<u>SOI model</u>

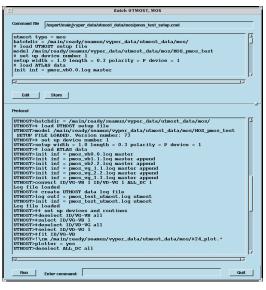
Honeywell FLORIDA FD FLORIDA NFD BSIM3SOI FD BSIM3SOI DD BSIM3SOI PD STAG SOI CEA/LETI User models

MESFET model

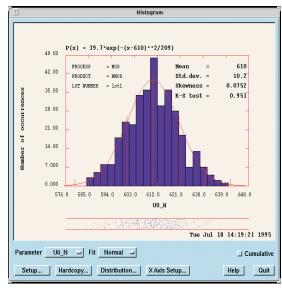
JFET Statz Curtice 1 Curtice 2 User models TriQuint TriQuint 3 Parker-Skellen

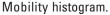
TFT models

Amorphous TFT Polysilicon TFT RPI a-Si RPI p-Si User models

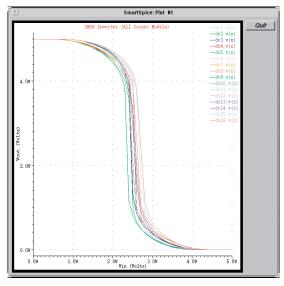




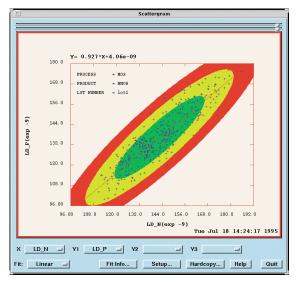




- Operates in manual, semi-automatic, automatic, and batch mode operation
 - · Includes technology modules for MOS, Bipolar, Diode, JFET, GaAs, SOI, TFT, and HBT
 - Automatically converts TCAD device characteristics from TCAD process and device simulations
 - Performs detailed parameter extractions on TCAD data in batch mode to develop nominal and worst-case models for a process under development
 - Stores model parameters and device characteristics in SPAYN format for statistical parametric analysis and worst-case model definitions



Statistical slew of MOS.



Scatter plot of drain length.

UTMOST III Operation

Spice Modeling Services

- Leader in supplying accurate SPICE models from wafers or packaged parts
- · Aggressive in providing cost effective models with rapid turnaround
- Model extraction provided for MOS, Bipolar, Diode, JFET, GaAs, SOI, TFT, HBT
- Extraction of DC, AC (s-parameters), capacitance, temperature, noise, SPICE parameters
- Temperature range from -55 degrees C to + 150 degrees C
- · All commercially available SPICE models supported
- Model validation in accordance with Global Semiconductor Alliance (GSA), Compact Modeling Council, and IEEE test procedure #P1485 recommendations
- · Worst-case and corner model generation

UTMOST III Inputs/Outputs





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